VN0104

N-Channel Enhancement-Mode Vertical DMOS FET

Features

- · Free from Secondary Breakdown
- · Low Power Drive Requirement
- · Ease of Paralleling
- Low C_{ISS} and Fast Switching Speeds
- · Excellent Thermal Stability
- · Integral Source-Drain Diode
- · High Input Impedance and High Gain

Applications

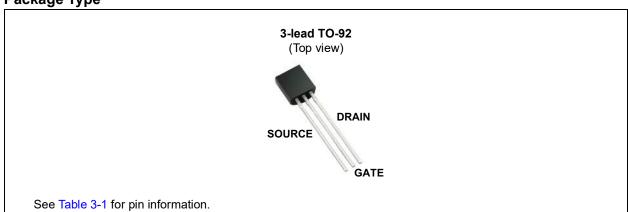
- · Motor Controls
- · Converters
- · Amplifiers
- · Switches
- · Power Supply Circuits
- Drivers (Relays, Hammers, Solenoids, Lamps, Memories, Displays, Bipolar Transistors, etc.)

General Description

The VN0104 Enhancement-mode (normally-off) transistors use a vertical DMOS structure and a well-proven silicon-gate manufacturing process. This combination produces a device with the power handling capabilities of bipolar transistors and the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, these devices are free from thermal runaway and thermally induced secondary breakdown.

Microchip's vertical DMOS FETs are ideally suited for a wide range of switching and amplifying applications where very low threshold voltage, high breakdown voltage, high input impedance, low input capacitance and fast switching speeds are desired.

Package Type



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings†

Drain-to-Source Voltage	BV _{DSS}
Drain-to-Gate Voltage	
Gate-to-Source Voltage	
Operating Ambient Temperature, T _A	
Storage Temperature, T _S	

† Notice: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

Electrical Specifications: $T_A = 25^{\circ}$ C unless otherwise specified. All DC parameters are 100% tested at 25°C unless otherwise stated. Pulse test: 300 µs pulse, 2% duty cycle

Parameter	Sym.	Min.	Тур.	Max.	Unit	Conditions
Drain-to-Source Breakdown Voltage	BV _{DSS}	40	_	_	V	V _{GS} = 0V, I _D = 1 mA
Gate Threshold Voltage	V _{GS(th)}	0.8	_	2.4	V	$V_{GS} = V_{DS}$, $I_D = 1 \text{ mA}$
Change in V _{GS(th)} with Temperature	$\Delta V_{GS(th)}$		-3.8	-5.5	mV/°C	$V_{GS} = V_{DS}$, $I_D = 1 \text{ mA}$ (Note 1)
Gate Body Leakage Current	I _{GSS}		_	100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
		_	_	1	μΑ	V _{GS} = 0V, V _{DS} = Maximum rating
Zero-Gate Voltage Drain Current	I _{DSS}	_	_	100	μΑ	V_{DS} = 0.8 Maximum rating, V_{GS} = 0V, T_A = 125°C (Note 1)
On-State Drain Current	1	0.5	1	_	Α	V_{GS} = 5V, V_{DS} = 25V
On-State Drain Current	I _{D(ON)}	2	2.5	_	Α	$V_{GS} = 10V, V_{DS} = 25V$
Static Drain-to-Source On-State Resistance	D		3	5	Ω	$V_{GS} = 5V, I_D = 250 \text{ mA}$
Static Dialif-to-Source Off-State Resistance	R _{DS(ON)}		2.5	3	Ω	$V_{GS} = 10V, I_D = 1A$
Change in R _{DS(ON)} with Temperature	$\Delta R_{DS(ON)}$	_	0.7	1	%/°C	V _{GS} = 10V, I _D = 1A (Note 1)

Note 1: Specification is obtained by characterization and is not 100% tested.

AC ELECTRICAL CHARACTERISTICS

Electrical Specifications: T _A = 25°C unless	s otherwi	se spe	cified. A	All AC p	paramete	ers are not 100% sample tested.
Parameter	Sym.	Min.	Тур.	Max.	Unit	Conditions
Forward Transconductance	G _{FS}	300	450	_	mmho	V_{DS} = 25V, I_{D} = 500 mA
Input Capacitance	C _{ISS}	_	55	65	pF	V _{GS} = 0V,
Common-Source Output Capacitance	Coss	_	20	25	pF	V _{DS} = 25V,
Reverse Transfer Capacitance	C _{RSS}	_	5	8	pF	f = 1 MHz
Turn-On Delay Time	t _{d(ON)}	_	3	5	ns	
Rise Time	t _r	_	5	8	ns	V _{DD} = 25V,
Turn-Off Delay Time	t _{d(OFF)}	_	6	9	ns	I _D = 1A, R _{GEN} = 25Ω
Fall Time	t _f	_	5	8	ns	- GEN
DIODE PARAMETER	_					
Diode Forward Voltage Drop	V _{SD}	_	1.2	1.8	V	V _{GS} = 0V, I _{SD} = 1A (Note 1)
Reverse Recovery Time	t _{rr}	_	400	_	ns	$V_{GS} = 0V$, $I_{SD} = 1A$

Note 1: All DC parameters are 100% tested at 25°C unless otherwise stated. Pulse test: 300 μs pulse, 2% duty cycle

TEMPERATURE SPECIFICATIONS

Parameter	Sym.	Min.	Тур.	Max.	Unit	Conditions
TEMPERATURE RANGE						
Operating Ambient Temperature	T _A	-55	_	+150	°C	
Storage Temperature	T _S	-55	_	+150	°C	
PACKAGE THERMAL RESISTANCE						
3-lead TO-92	θ_{JA}	_	132	_	°C/W	

THERMAL CHARACTERISTICS

Package	I _D (Note 1) (Continuous) (mA)	I _D (Pulsed) (A)	Power Dissipation at T _A = 25°C (W)	I _{DR} (Note 1) (mA)	I _{DRM} (A)
3-lead TO-92	350	2	1	350	2

Note 1: I_D (continuous) is limited by maximum rated T_J .

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g. outside specified power supply range) and therefore outside the warranted range.

2.5

FIGURE 2-5:

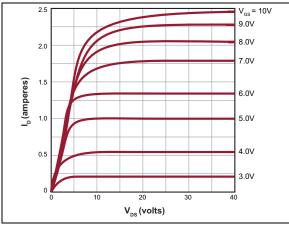


FIGURE 2-1: Output Characteristics.

1.0

V_{DS} = 25V

0.8

T_A = -55°C

25°C

0.2

0.2

0.4

0.6

0.8

1.0

I_D (amperes)

FIGURE 2-4: Saturation Characteristics.

2.0

1.0

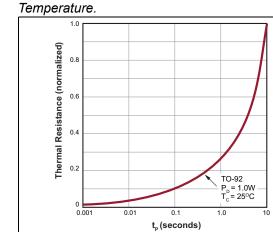
0

2.5

TO-92

T_c (°C)

FIGURE 2-2: Transconductance vs. Drain Current.



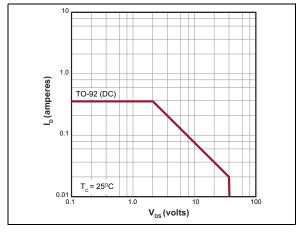


FIGURE 2-6: Thermal Response Characteristics.

FIGURE 2-3: Maximum Rated Safe Operating Area.

Power Dissipation vs. Case

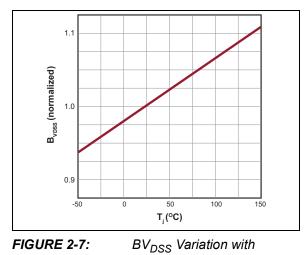


FIGURE 2-7: Temperature.

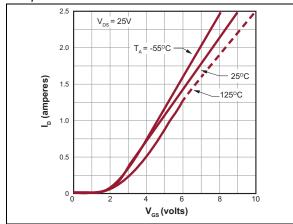


FIGURE 2-8: Transfer Characteristics.

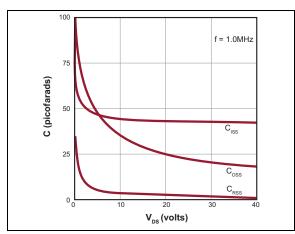


FIGURE 2-9: Capacitance vs. Drain-to-Source Voltage.

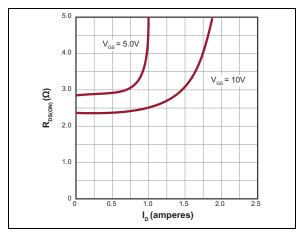
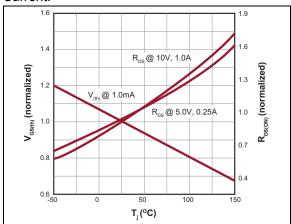


FIGURE 2-10: On-Resistance vs. Drain Current.



V_(th) and R_{DS} Variation with **FIGURE 2-11:** Temperature.

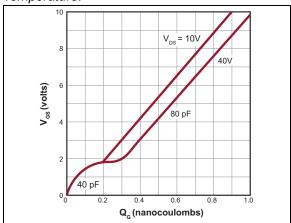


FIGURE 2-12: Gate Drive Dynamic Characteristics.

VN0104

3.0 PIN DESCRIPTION

The details on the pins of VN0104 are listed in Table 3-1. Refer to **Package Type** for the location of the pins.

TABLE 3-1: 3-LEAD TO-92 PIN FUNCTION TABLE

Pin Number	Pin Name	Description
1	Source	Source
2	Gate	Gate
3	Drain	Drain

4.0 FUNCTIONAL DESCRIPTION

Figure 4-1 illustrates the switching waveforms and test circuit for VN0104.

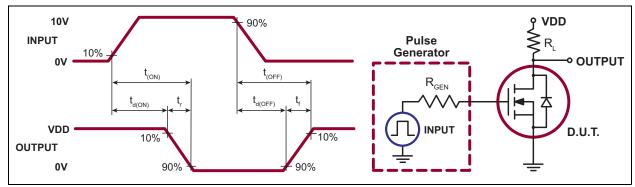


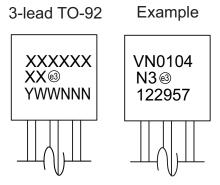
FIGURE 4-1: Switching Waveforms and Test Circuit.

TABLE 4-1: PRODUCT SUMMARY

Device	BV _{DSS} /BV _{DGS} (V)	R _{DS(ON)} (Maximum) (Ω)	I _{DSS} (Minimum) (A)
VN0104	40	3	2

5.0 PACKAGING INFORMATION

5.1 Package Marking Information

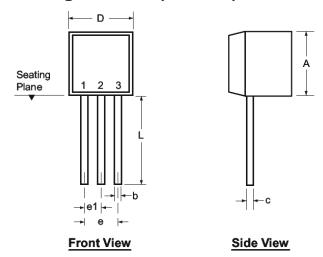


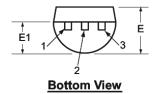
Legend: XX...X Product Code or Customer-specific information
Y Year code (last digit of calendar year)
YY Year code (last 2 digits of calendar year)
WW Week code (week of January 1 is week '01')
NNN Alphanumeric traceability code

Byb-free JEDEC® designator for Matte Tin (Sn)
This package is Pb-free. The Pb-free JEDEC designator (a)
can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for product code or customer-specific information. Package may or not include the corporate logo.

3-Lead TO-92 Package Outline (L/LL/N3)





Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

Symb	ool	Α	b	С	D	E	E1	е	e1	L
	MIN	.170	.014 [†]	.014 [†]	.175	.125	.080	.095	.045	.500
Dimensions (inches)	NOM	-	-	-	-	-	-	-	-	-
(MAX	.210	.022 [†]	.022†	.205	.165	.105	.105	.055	.610*

JEDEC Registration TO-92.
* This dimension is not specified in the JEDEC drawing.
† This dimension differs from the JEDEC drawing.

Drawings not to scale.



NOTES:

APPENDIX A: REVISION HISTORY

Revision A (September 2021)

- Converted and merged Supertex Doc# DSFP-VN0104 to Microchip DS20005975A
- · Added a pin function table
- Changed the package marking format
- Removed the 3-Lead TO-92 N3 P002, P003, P005 and P014 media types for VN0104 to align packaging specifications with the actual BQM
- Made minor text changes throughout the document

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

PART NO	<u> </u>		- <u>X</u> -	<u>×</u>
Device Device	Packa Optic		Environmental	l Media Type
Device:	VN0104	=	N-Channel Enhanceme DMOS FET	nt-Mode Vertical
Package:	N3	=	3-lead TO-92	
Environmental:	G	=	Lead (Pb)-free/RoHS-co	ompliant Package
Media Types:	(blank)	=	1000/Bag for an N3 Pag	ckage
	P003	=	2000/Reel for an N3 Pa	ckage
	P013	=	2000/AMMO Pack for a	n N3 Package

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